Photoresist reflow for IBE etch process

Silicon test wafer
Ti/Pt sputtered (Spider)

**Litho AZ10xt 1um (ACS + MA6)**

**No Reflow**
- Uniform color everywhere
- Straight edges
- Sharp corners

**Reflow 2min @125°C**
- Colors at edges
- Rounded edges
- Rounded corners
Photoresist reflow for IBE etch process

Silicon test wafer
Ti/Pt sputtered (Spider)

**Litho AZ10xt 1um (ACS + MA6)**

No Reflow

- Uniform color everywhere
- Straight edges
- Sharp corners

Reflow 2min @125°C

- Colors at edges
- Rounded edges
- Rounded corners
Photoresist reflow for IBE etch process

Ti/Pt sputtered (Spider)
Litho AZ10xt 1um (ACS + MA6)
Medium_IBE, -10deg, 50% over-etch

No Reflow

Reflow 2min @125°C

PR-Metal limit not clear
High faceting of PR
High sidewall redeposition

PR-Metal limit clear
No faceting of PR
No sidewall redeposition
Photoresist reflow for IBE etch process

Ti/Pt sputtered (Spider)
Litho AZ10xt 1um (ACS + MA6)

Medium_IBE, -10deg, 50% over-etch

No Reflow

Reflow 2min @125°C

PR-Metal limit not clear
High faceting of PR
High sidewall redeposition

PR-Metal limit clear
No faceting of PR
No sidewall redeposition
Photoresist reflow for IBE etch process

Ti/Pt sputtered (Spider)
Litho AZ10xt 1um (ACS + MA6)

**Medium** IBE, 70% @ -45deg, 30% @ -5deg, 10% over-etch

No Reflow

Reflow 2min @125°C